

1. Description

3. Top View

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.33 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Optional V_{DD} LED indicator
- Decoupling capacitor included
- Optional I²C pull-up resistors



Note 1 All sizes in inches.

LED current limit resistor (optional) VDD LED indicator (optional) Pins 0 LED1 G RI G Θ PIN6 (GPI) G 0 PIN1 (GPIO) C Ð PIN2 (GPIO) O G PIN3 (GPIO) G 0 PIN4 (GPIO) C Ð PIN5 (GPIO) C Ξ PIN8 (SCL/GPIO) NO) 0 C PIN19 (GPIO) 0 PIN18 (GPIO) C Chip package type Chip package number 20 UI N1 VOUTS . GND GND GreenPAK chip IC1 VOUT2 VDD Chip decoupling capacitor GND C16 VOUTI GND . UINO VOUTO PIN12 (LDO VINO) GND C

4. Bottom View





5. Board Schematic



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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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